

**REMARKS**

In the present Amendment, claim 7 has been amended to replace “formed on” with --above--. This amendment is further supported by the specification, for example, in Figs. 2-4.

Claim 1 has previously been canceled.

No new matter has been added and entry of the Amendment is respectfully requested. Upon entry of the Amendment, claims 2-12 will be all the claims pending in the application.

**I. Response to Rejection Under 35 U.S.C. § 112, Second Paragraph**

In Paragraph No. 2 of the Office Action, claims 7-12 were rejected under 35 U.S.C. § 112, second paragraph, as allegedly being indefinite.

Applicants respectfully submit that the present claims are not indefinite. As described above, Applicants have amended claim 7, from which claims 8-12 depend, to replace “formed on” with --above--, thus more clearly indicating that the adhesive layer is not necessarily formed *directly* on, i.e., in contact with, the substrate. Accordingly, the Examiner is respectfully requested to reconsider and withdraw the rejection.

**II. Response to Rejection Under 35 U.S.C. § 103**

In Paragraph No. 3 of the Office Action, claims 2-12 were rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over either JP Abstract 11-166164 (“JP ‘164”) or its complete translation, or, alternatively, “applicants’ admissions” regarding the prior art on page 1 of the specification, modified by Shibata et al (US 2001/0020515), each taken in view of the complete English translation of JP 9201910 (“JP ‘910”).

Applicants submit herewith a verified English translation of their priority document, i.e., JP 2000-142513, to obtain the benefit of their priority claim. Applicants’ priority date of May

15, 2000 is prior to the February 28, 2001 § 102(e) date of Shibata et al. Accordingly, Shibata et al is not prior art against the present claims in this § 103 rejection. Exemplary support of the present claims in JP 2000-142513 is summarized below:

<u>Present claims</u>	<u>Support in JP 2000-142513</u>
2	claim 2
3	claims 1 and 3; Paragraph Nos. [0027] and [0030]
4 and 5	claims 4 and 5, respectively
6	Paragraph No. [0027] and Examples
7	Paragraph No. [0036]
8	Paragraph No. [0034] and Example 3
9	claim 2; and Paragraph No. [0036]
10	claim 4; and Paragraph No. [0036]
11	claim 5; and Paragraph No. [0036]

Furthermore, JP '910 discloses adding heat-expandable microspheres to an adhesive layer together with a conductive material. The purpose of adding a conductive material to an adhesive layer in JP '910 is to prevent localized electric charge in the adhesive layer when a tape is peeled at a high speed. Further, where the adhesive layer has a large thickness, static electrification in the adhesive layer can be prevented. However, JP '910 does not disclose or suggest applying an antistatic agent to an adhesive layer. Accordingly, Applicants respectfully submit that one skilled in the art would not have been motivated to apply an antistatic agent of JP '910 to the substrate of JP '164 or "applicants' admissions."

In view of the above, Applicants respectfully submit that the present claims are not obvious over JP '164 or "Applicants' admissions" in view of JP '910 and that the rejection should be withdrawn.

**III. Conclusion**

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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